

Item # Tpcm 670, Tpcm™ 670 Series Phase Change Material



Tpcm™ 670 Series Phase Change Material

Tpcm™ 670 is a high performance, inherently tacky, easy to rework phase change thermal interface material. Developed specifically to meet the high thermal conductivity and low thermal resistance requirements of Intel® mobile processors. Tpcm™ 670 is optimized for Intel's Penryn Quad-Core mobile processor.

SPECIFICATIONS

Construction and Composition	Non-reinforced film
Color	Gray
Thickness	.008 inches 0.20 mm
Shelf Life	1 year
Operating Temperature	52 °C
Phase Change Softening Range	~48 °C
Thermal Resistance at 50 psi	0.013 °C-in ² /W
Thermal Conductivity	4.3 W/m-K
Specific Gravity	2.50 g/cm ³
Thickness Tolerance	+/-0.001 inches 0.025 mm